

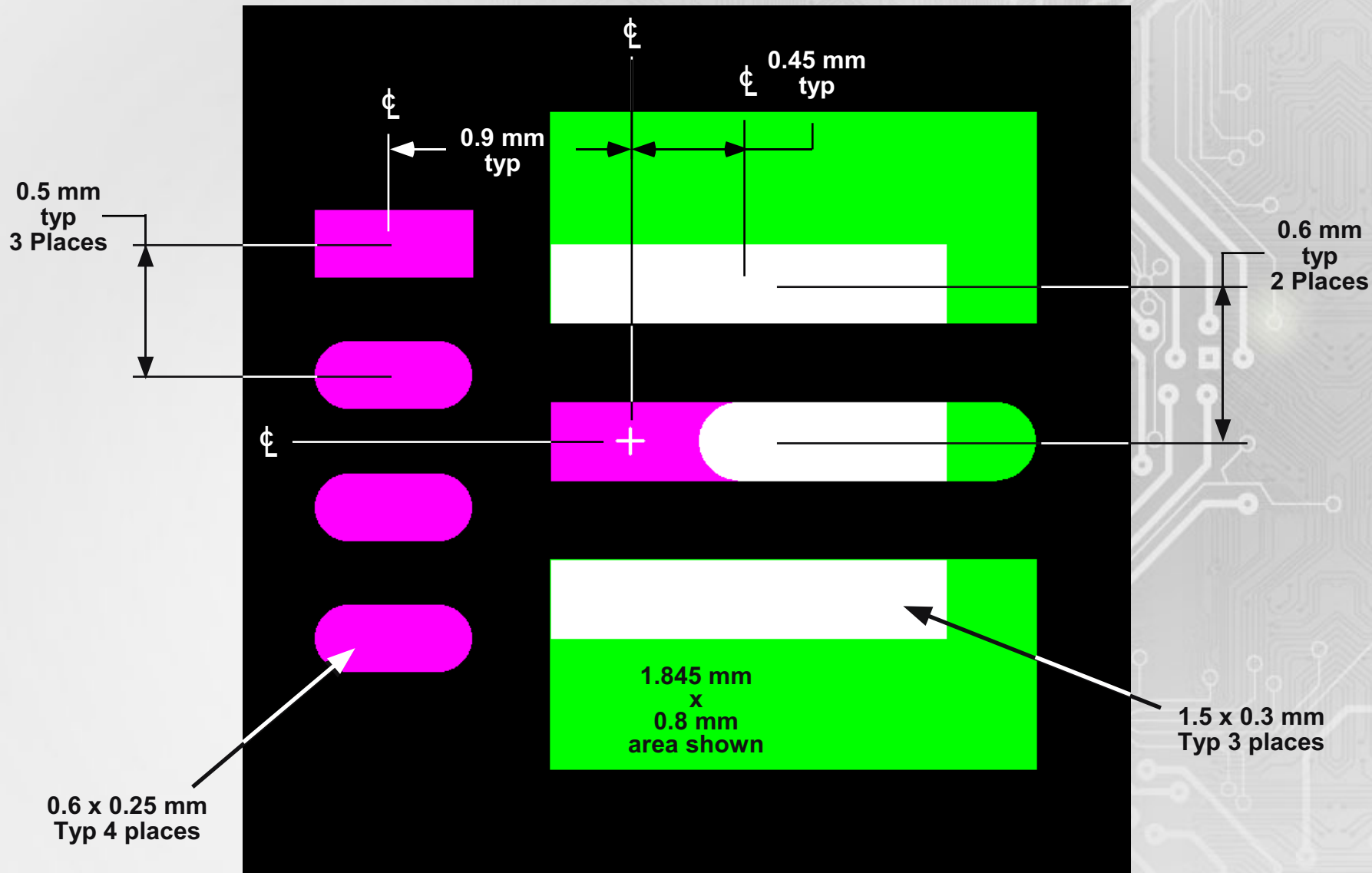
RLT0007A

Land Pattern Example

Vias under package

Analog Packaging

18-Dec-2013



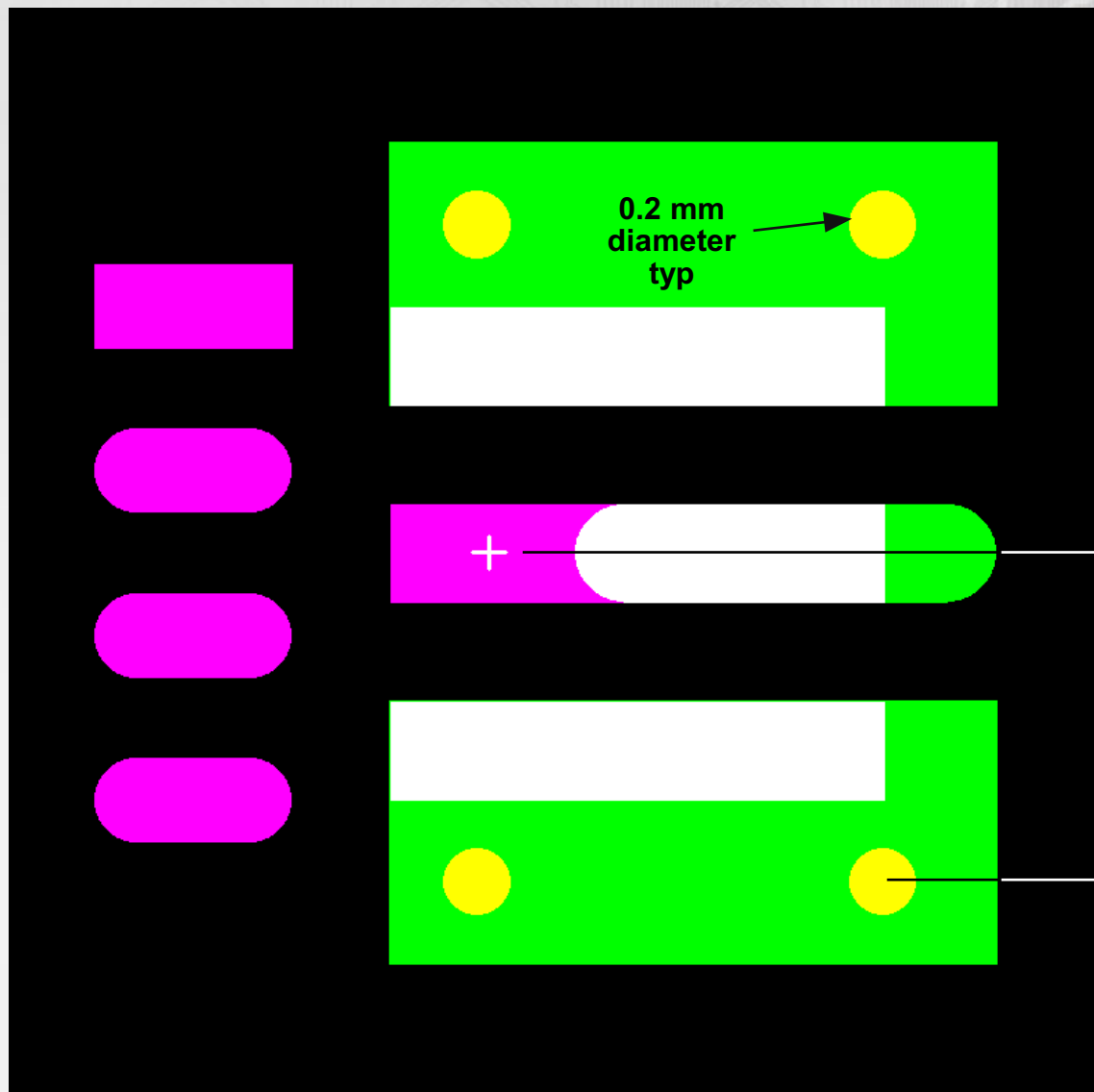
TOP ETCH

 = Exposed FR4

 = Additional metal

 = Metal pads (highlighted)

NOTE:
Refer to package mechanical drawing at the website for complete mechanical dimensions.



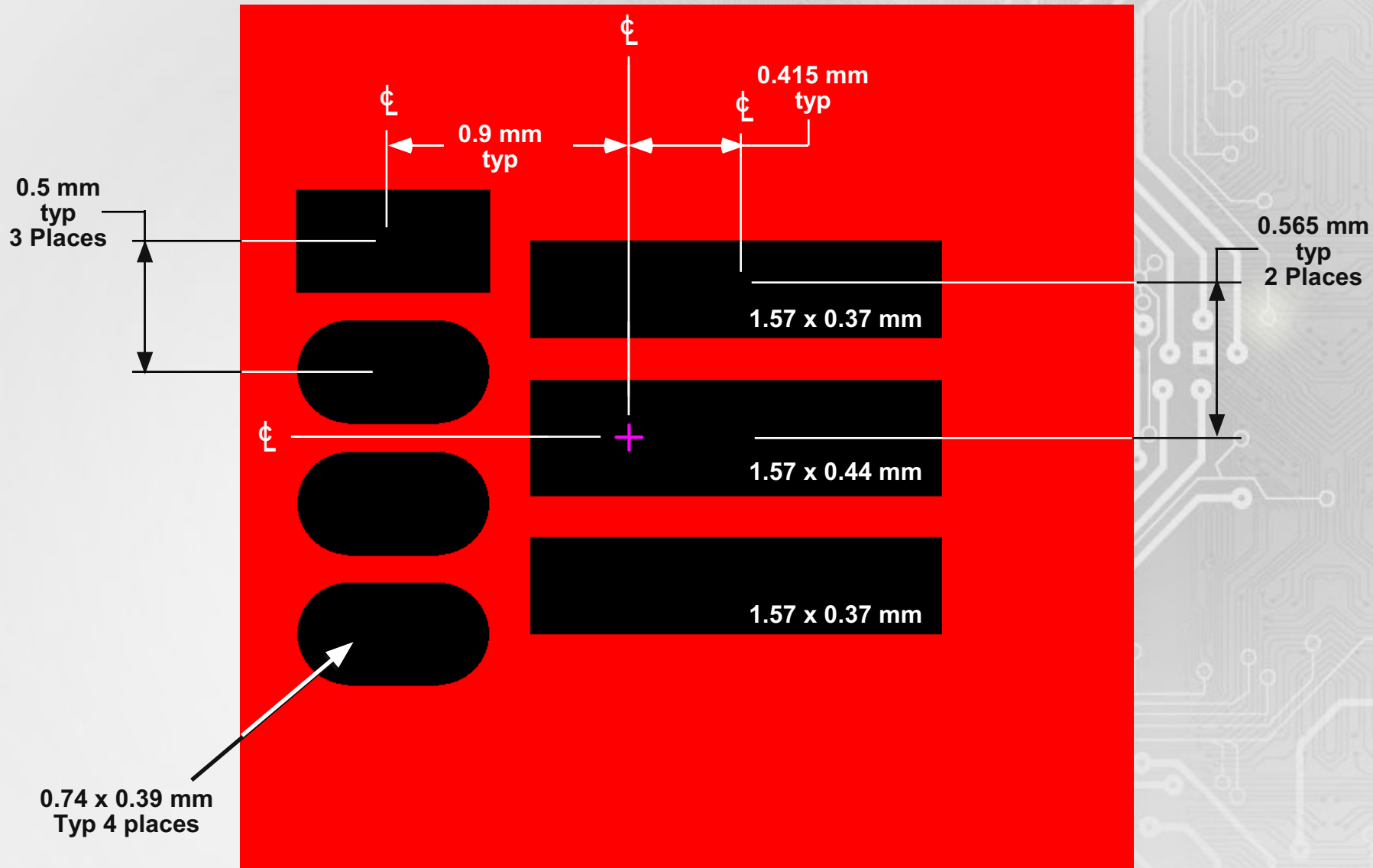
TOP ETCH with VIAS

 = Exposed FR4

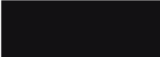
 = Exposed metal

 = Vias

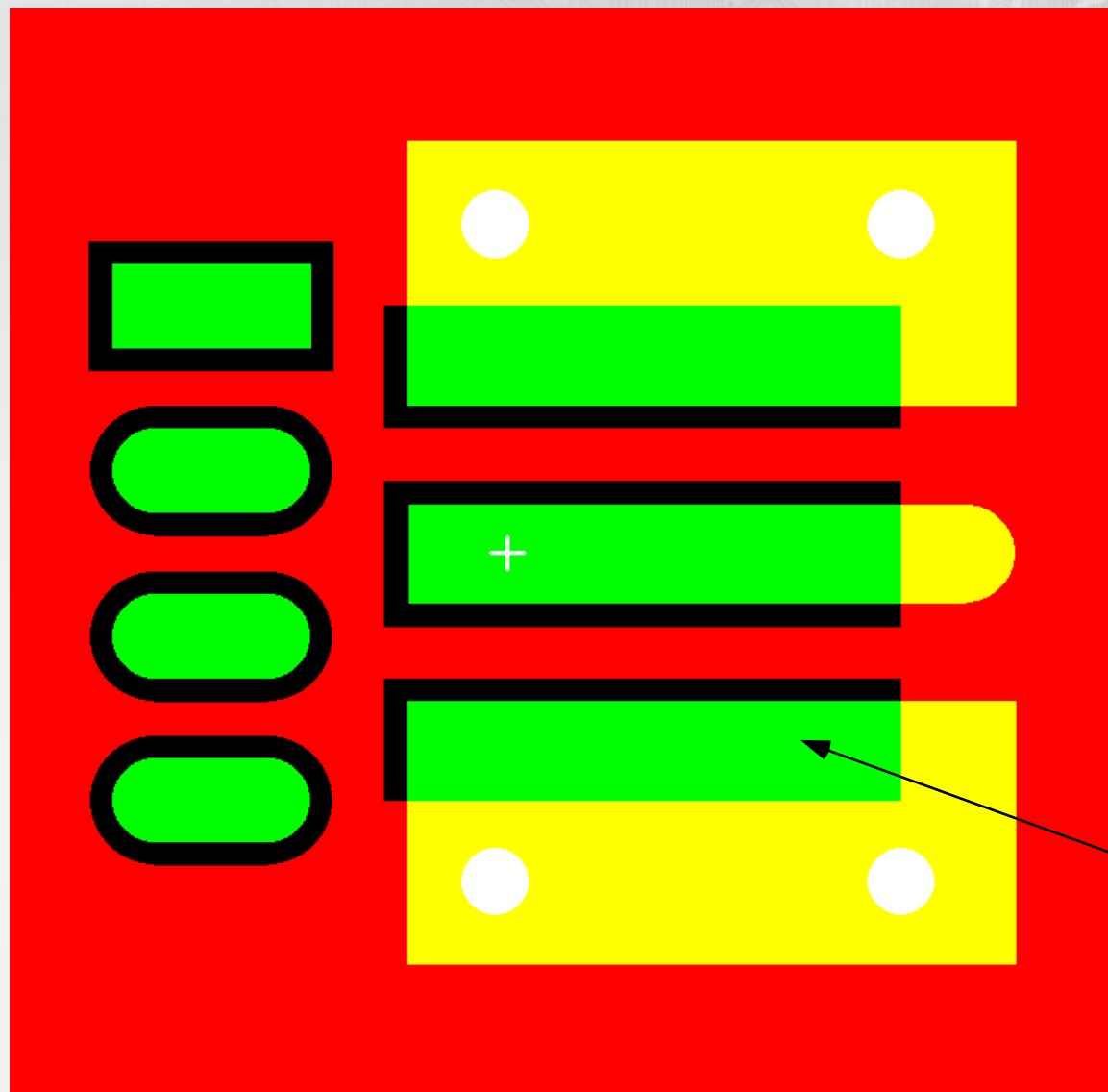
 = Metal pads (highlighted)



TOP SOLDERMASK

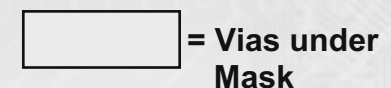
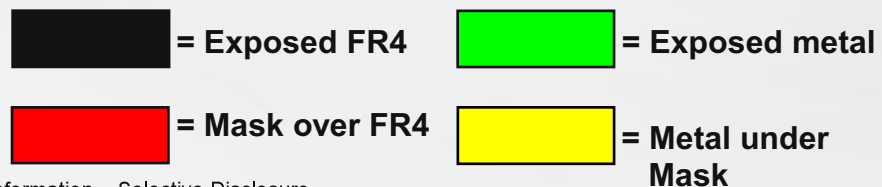
 = Exposed FR4

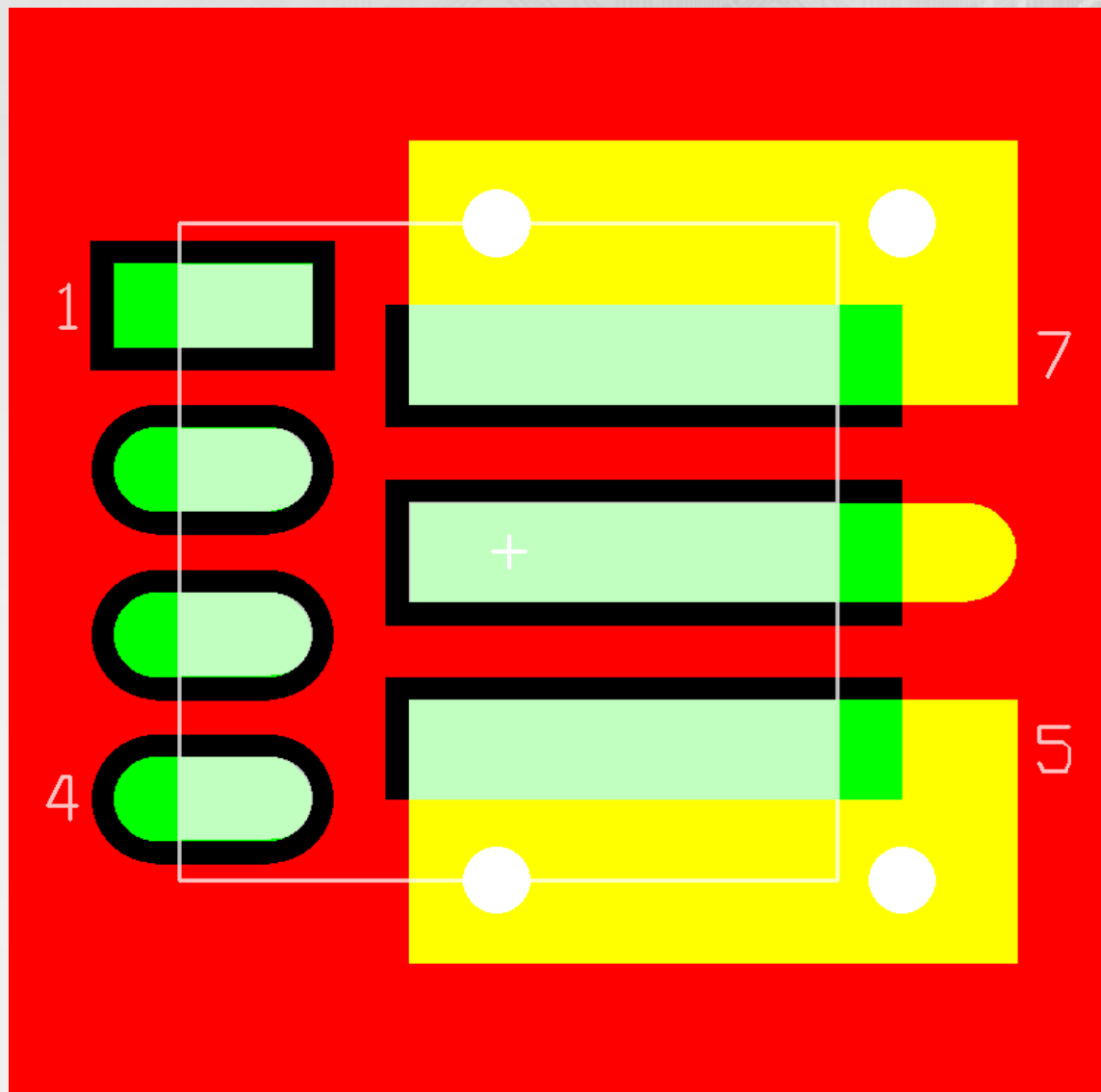
 = Mask over FR4



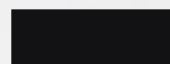
1.5 x 0.3 mm
exposed metal
typ 3 places

TOP ETCH + SOLDERMASK + VIAS





PACKAGE ON FOOTPRINT



= Exposed FR4



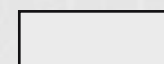
= Exposed metal



= Mask over FR4



= Metal under
Mask

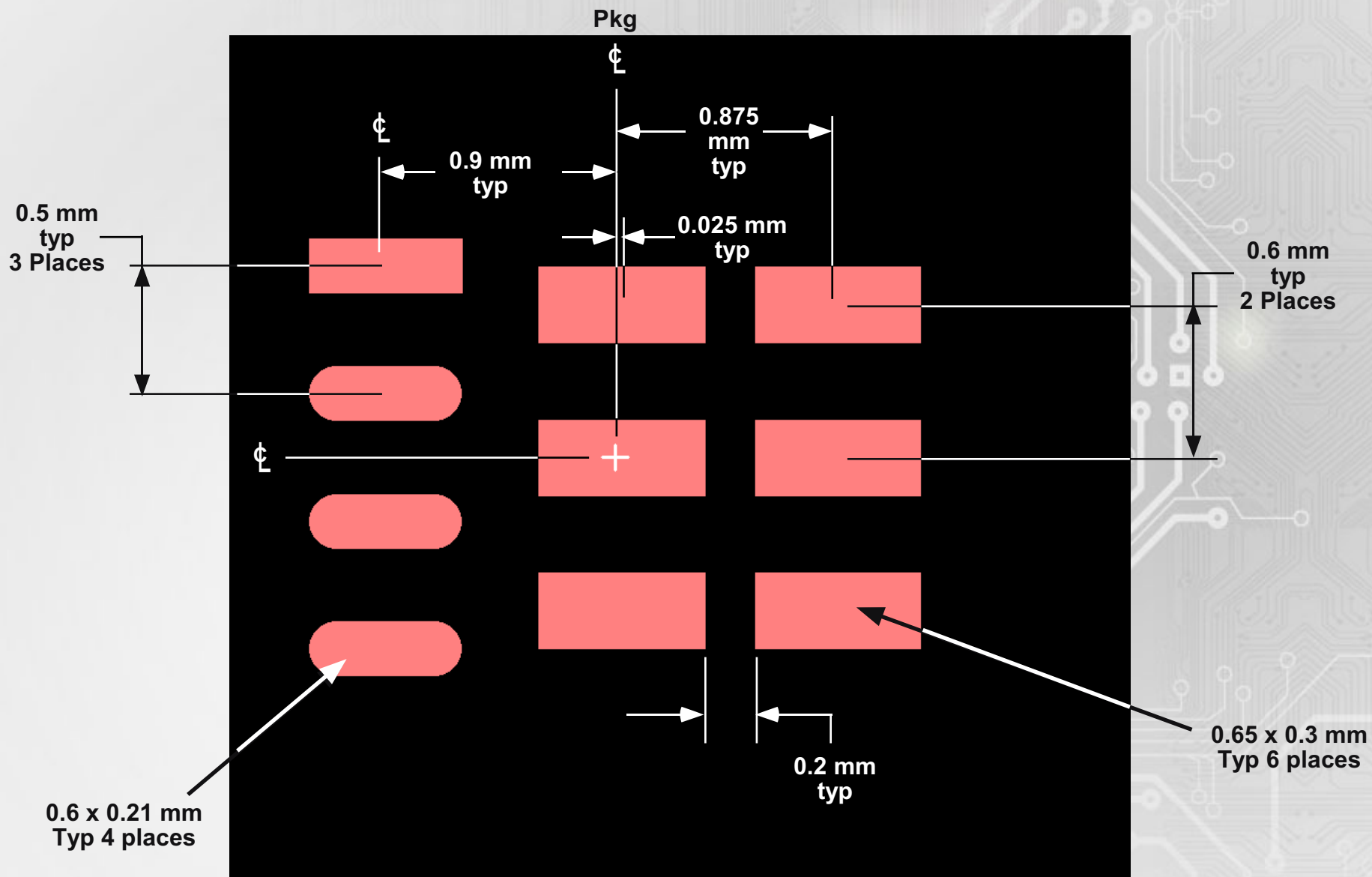


= Vias under
Mask



= Package
pads



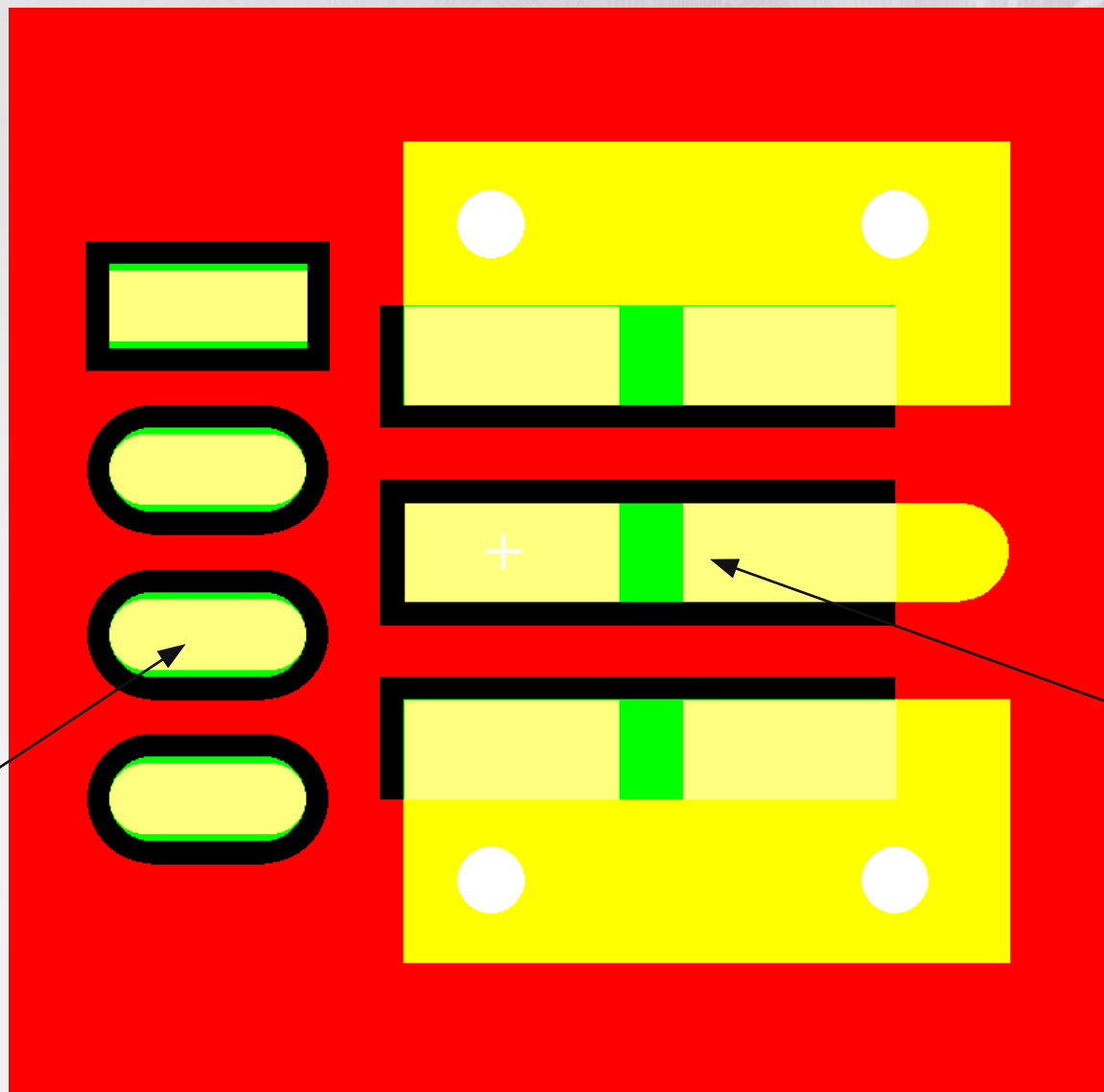


TOP SOLDERPASTE

Note:
Recommended stencil thickness is
0.1mm (0.004") to allow proper
deposition of the solderpaste.

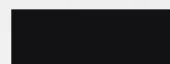
 = Paste

84% I/O pad
paste
coverage



85% exposed
pad paste
coverage
under package

TOP ETCH + SOLDERMASK + SOLDERPASTE + VIAS

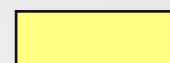
 = Exposed FR4

 = Exposed metal

 = Vias under Mask

 = Mask over FR4

 = Metal under Mask

 = Paste over Metal